Paragon Semiconductor Lighting Technology

PSLT

ParagonLED

Specifications

Product Type : CBAC-84-36185-120V-30

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Paragon Semiconductor Lighting Technology Co., Ltd.
Headquarters: 3F., No.369, Sec. 2, Wenhua 2nd Rd.,Linkou Dist., New Taipei City 244, Taiwan (R.O.C.)
TEL: +886-2-2602-1066 FAX: 886-2-2601-0508

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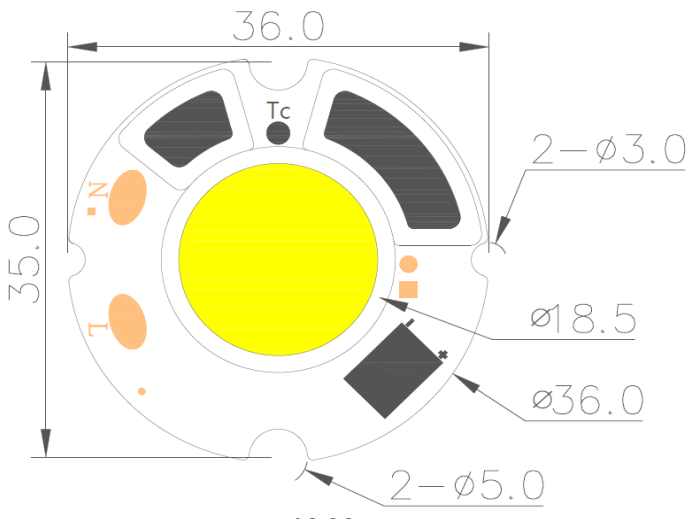
1. General Description

(1) Naming rule

CBAC- 84 -36185-120V- 30

Product Series type : C
Power Efficiency : B
Driving conditionl : AC Driven
Numbers of chips on board : 84
Outline Dimension : 36mm
Emission area : 18.5mm
Voltage : 120V
Color Temperature : 3000K

(2) Outline Dimensions (Unit : mm / Tolerance: 0.2mm)



Thickness : 1.0±0.1mm

2. Electro-Optical Characteristics

(1) Absolute Maximum Rating

Parameter	Symbol	Value	Unit
Power Dissipation	PD	22	W
Forward Current	IF	-	mA
Forward Voltage	VF	110 ~ 140	V
Operating Temperature	Topr	-60 ~ +105	℃
Storage Temperature	Tstg	-60 ~ +105	℃
Assembly process temperature	Tsol	<300℃ , 5 secs	

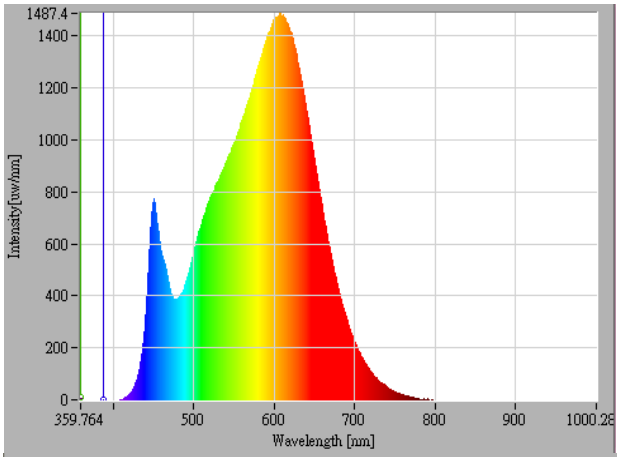
(2) Electro-Optical Characteristics

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Forward Voltage	VF	-	110	120	140	V
Reverse Current	IR	-	-	-	-	μA
Luminous Intensity	Φv	VF=120V	-	1540	-	Lm
Color rendering	Ra	VF=120V	-	90	-	

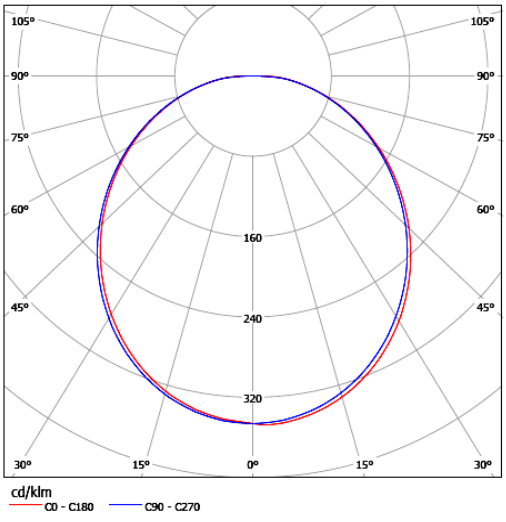
Notice: Operating voltage of CBAC-084 product varies from 110V~140V，users must keep the temperature of solder joint point under 105℃ (with suitable heat sink), or may cause Serious luminous decay. We DO NOT guarantee of improper use.

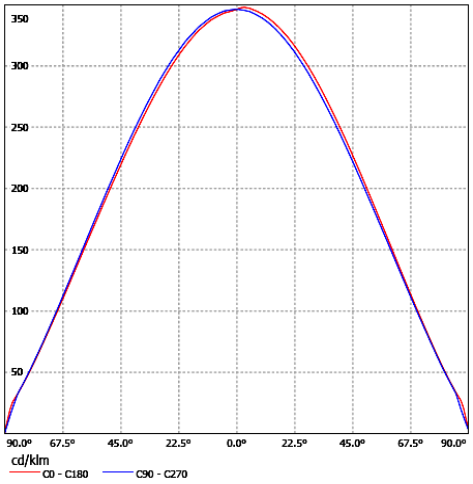
(3) Characteristics

Spectrum

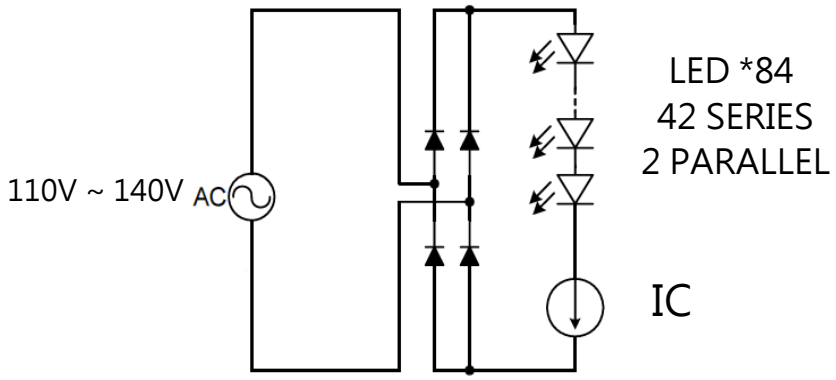


Candle Power Distribution & Cartesian Coordinate

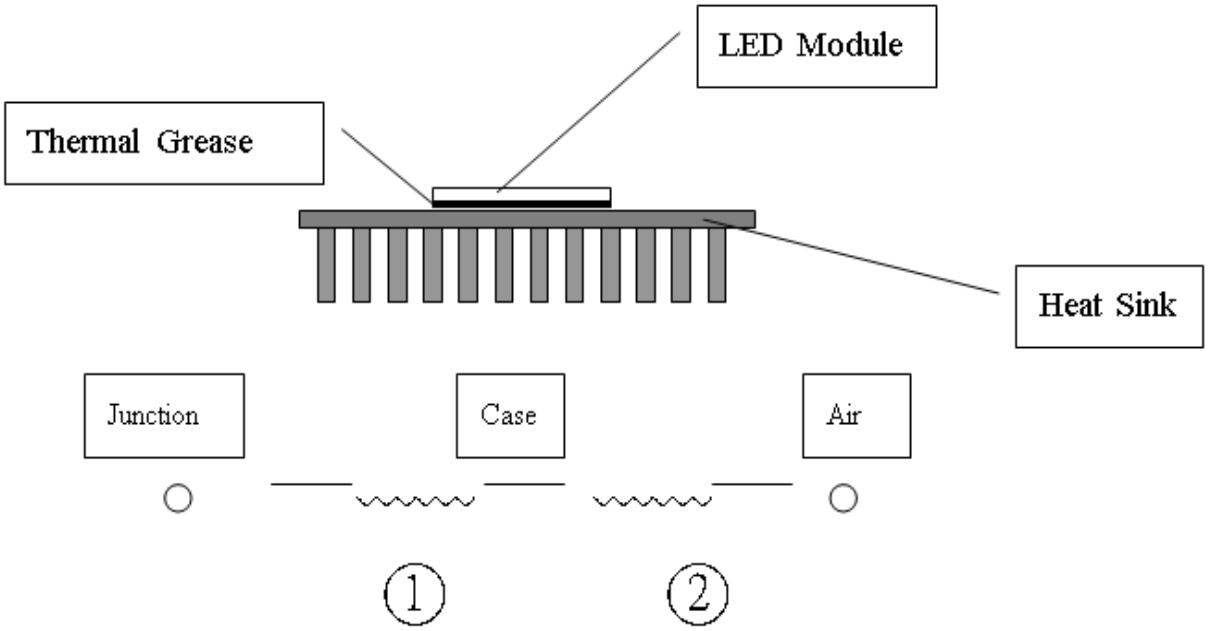




(4) Layout



3. Junction Temperature Measurement



①Thermal resistance of Junction to Case without heat sink : 10(℃/W) 〔Reference Value〕

②Thermal resistance of Case to Ambient Air: Depending on what kind of heat sink users choose. In ideal thermal dissipation situation, the thermal resistance is about 1~2 ℃/W.

4. Reliability Test

Test Item	Test Conditions	Number of failed
High Temperature Storage Test	Tstg= +105°C，x1,000 hrs	0/20
Low Temperature Storage Test	Tstg=-40°C，x1,000 hrs	0/20
Continous Light-on Test	Ta= 25°C，RH=65%，x1,000 hrs	0/20
Boiling Test	Ta=100°C，RH=100%，X180mins	0/20
Thermal Cycle Test	- 40°Cx30mins，80°Cx30mins，100cycles	0/20

Measuring Item	Measuring Condition	Judging Criteria of Failure
Forward Voltage	VF=120V	> 0 x 1.1
Total Luminous Flux	VF=120V	< L x 0.85

Dielectric Breakdown Voltage (Vac) of Thremal Pad must >4 KV

WARNING : Please ground lighting fixtures while designing lamps.
If any damage or defect of LED caused without grounding, we do not guarantee of improper use.